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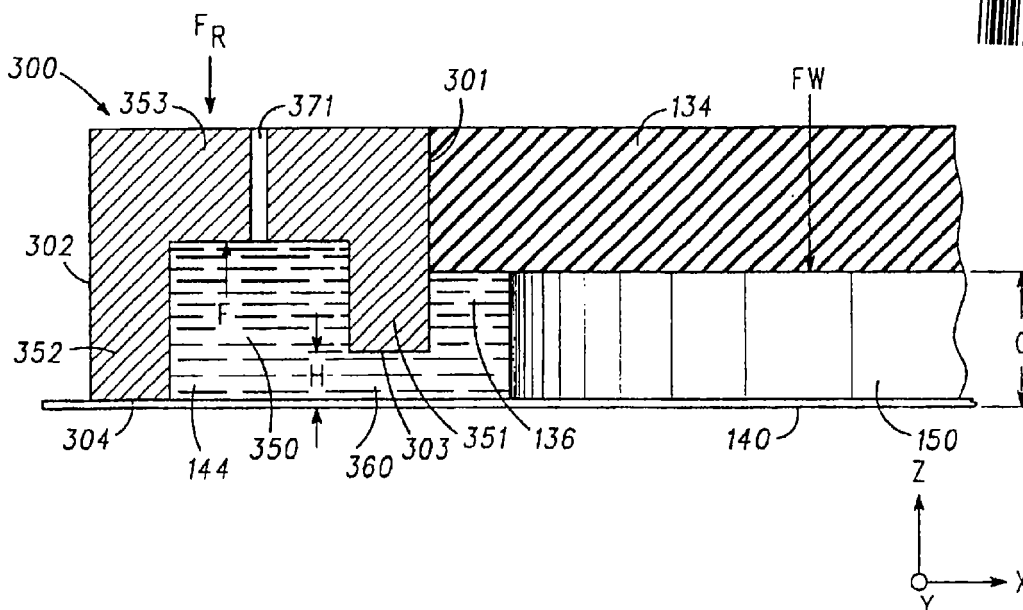
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(54) Title: RETAINING RING FOR CHEMICAL-MECHANICAL POLISHING HEAD, POLISHING APPARATUS, SLURRY CYCLE SYSTEM, AND METHOD



(57) Abstract: In a chemical-mechanical polishing machine (101) where a polishing head (100) holds a wafer (150) against a polishing pad (140), a retaining ring (300) that surrounds the wafer (150) has an open chamber (350) to distribute pressurized slurry (144) to the polishing pad (140) and to the periphery (153) of the wafer (150).